



FOR IMMEDIATE RELEASE

**Buc, France, March 2009, 2<sup>nd</sup> – Radiation Tolerant Memory Stacks ready to Fly on NASA JPL Kepler Telescope**

NASA Kepler Telescope mission embedding Radiation Tolerant Memory stacks will be launched with a Delta-II Rocket on Friday, March 6, from Pad 17-B at Cape Canaveral.

Kepler is a space borne telescope designed to search the nearby region of our galaxy for Earth-size planets orbiting in the habitable zone of stars like our sun. The challenge of this space mission is to look at a large number of stars in order to statistically estimate the total number of Earth-size planets orbiting sun-like stars in the habitable zone.

The one-meter diameter (39-inch) telescope equipped with the equivalent of 42 high quality digital cameras will continuously monitor the brightness of 100,000 stars in our galaxy.

3D Plus Radiation Tolerant Memory stacks are embedded in the mission data recorder and enable the high reliability storage of the mission's mass information.

Kepler mission development is managed by NASA's Jet Propulsion Laboratory, Pasadena, Ca. Ball Aerospace and Technologies Corporation of Boulder, Co, is responsible for developing the Kepler flight system and supporting mission operations.

Real time launch and mission information can be found on the following URL:

JPL: [http://planetquest.jpl.nasa.gov/Kepler/kepler\\_index.cfm](http://planetquest.jpl.nasa.gov/Kepler/kepler_index.cfm)

NASA: <http://www.kepler.arc.nasa.gov/>

BALL Aerospace: <http://www.ballaerospace.com/page.jsp?page=72>

***About 3D PLUS company:***

Founded in 1995 as a spin-off of Thales, 3D Plus has become a worldwide actor for the advanced high density 3D package and die stacking technology meeting the demand for high reliability, extreme performance and very small size electronics.

Its portfolio of patented and very advanced stacking technologies starts with Package scale upward to die-size and wafer-level packaging techniques and provides leading edge, highly integrated and rugged modules embedding Active, Passive, Opto-electronics and MEMS/MOEMS components.

In 2009, with more than 30 000 modules in Space, and, with more than 9 years of Flight Heritage with no Failure, 3D Plus is the largest Space qualified catalogue products and custom System-In-Packages (SiPs) manufacturer in Europe.

3D Plus products fly in numerous satellite programs for all major space agencies worldwide. Most of the Space missions launched recently, or, to be launched soon embeds 3D Plus Modules. Current customers' portfolio includes the major Aerospace prime contractors and equipment manufacturers spread over more than 30 countries.

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